

*Non-traditional  
Machining Processes*



Introduction to Manufacturing  
Processes

# Outline



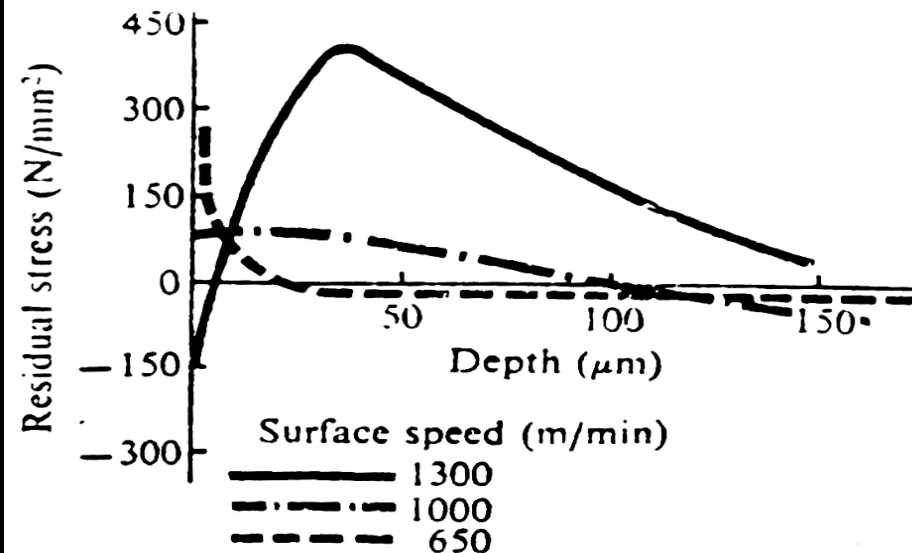
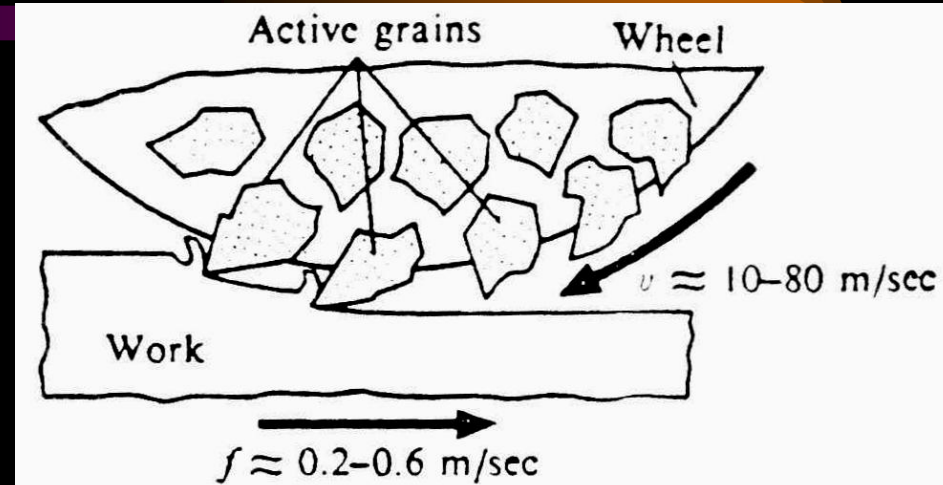
- Abrasive Grinding
- Non-traditional Machining Processes
  - Ultrasonic Machining
  - Abrasive Water Jet Machining
  - Chemical Machining
  - Electro-chemical Machining
  - Electro-chemical Grinding
  - Electrodischarge Machining
  - Laser Beam Machining
  - Case Studies
  - Overall Process comparisons

# *Grinding*

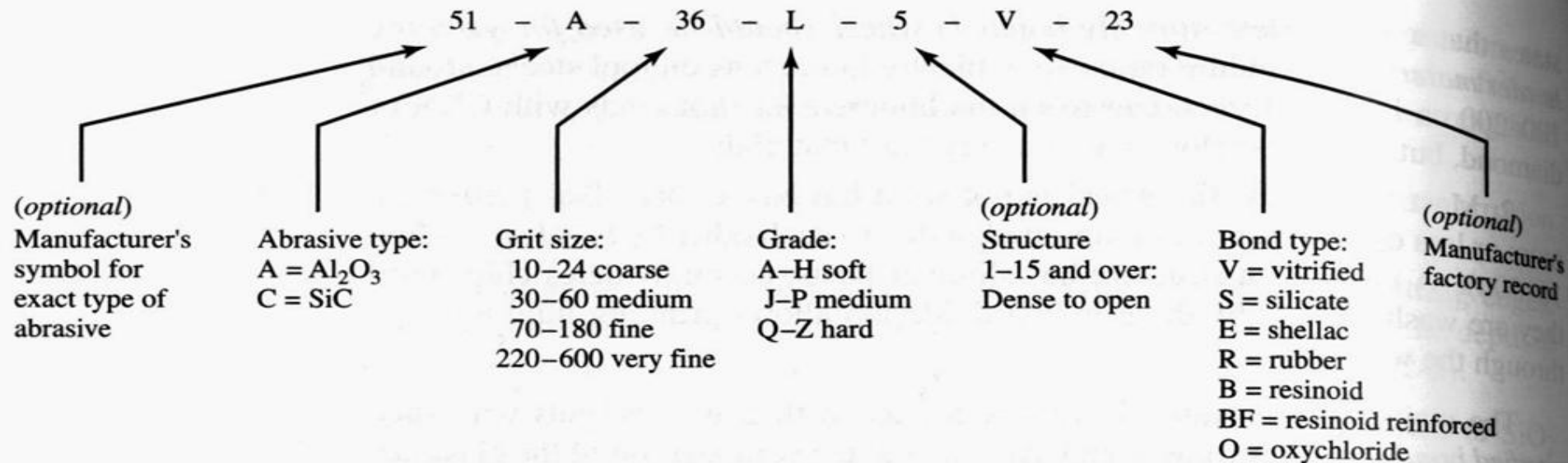


# Abrasive Grinding

- Can be viewed as multiple very small cutting edges
- Results in a very fine finish
- Can leave residual stresses
- Slow, small material removal rates
- Sparking out



# Standard Grinding Wheel Designation

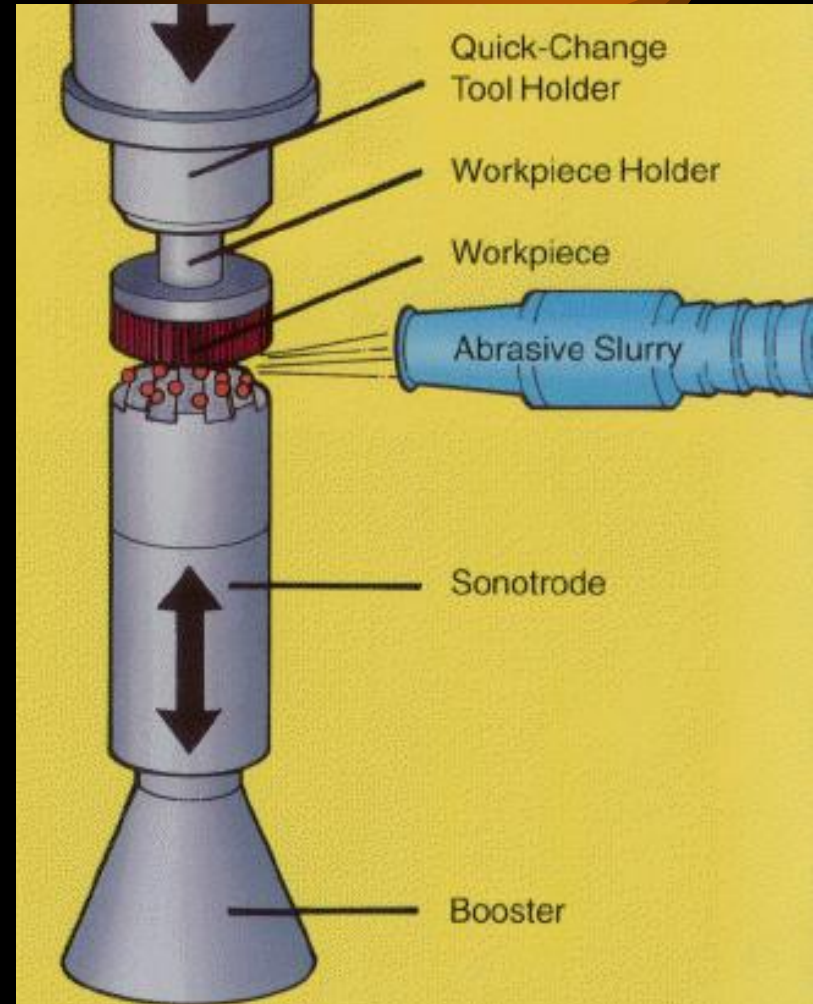


- While this is specific to grinding, realize that there are similar standard designations in most industries
- Take the time to learn the standard designations early so that you can speak intelligibly with those within the industry.



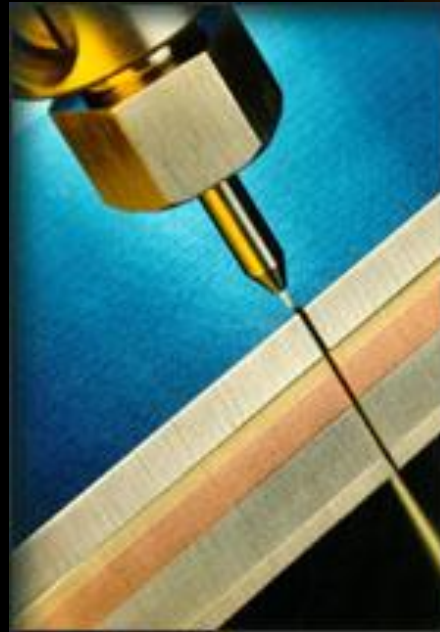
# Ultrasonic Machining

- Ultrasonic vibration (20,000 Hz) of very small amplitudes (0.04-0.08 mm) drive the form tool (sonotrode) of ductile material (usually soft steel)
- An abrasive slurry is flowed through the work area
- The workpiece is brittle in nature (i.e. glass)
- The workpiece is gradually eroded away.

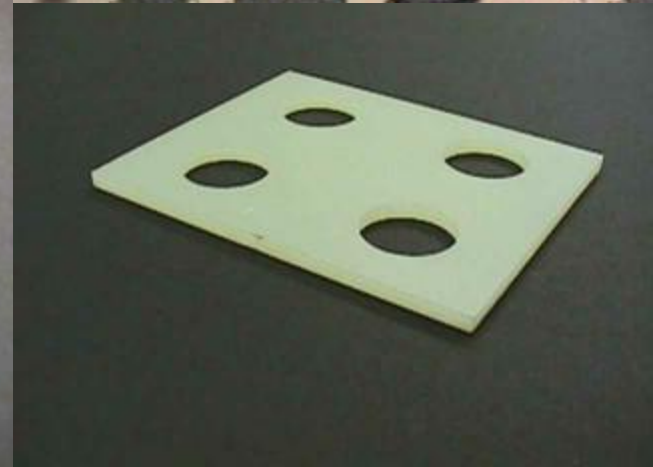




# *Waterjet and Abrasive Waterjet (AWJ) Cutting*



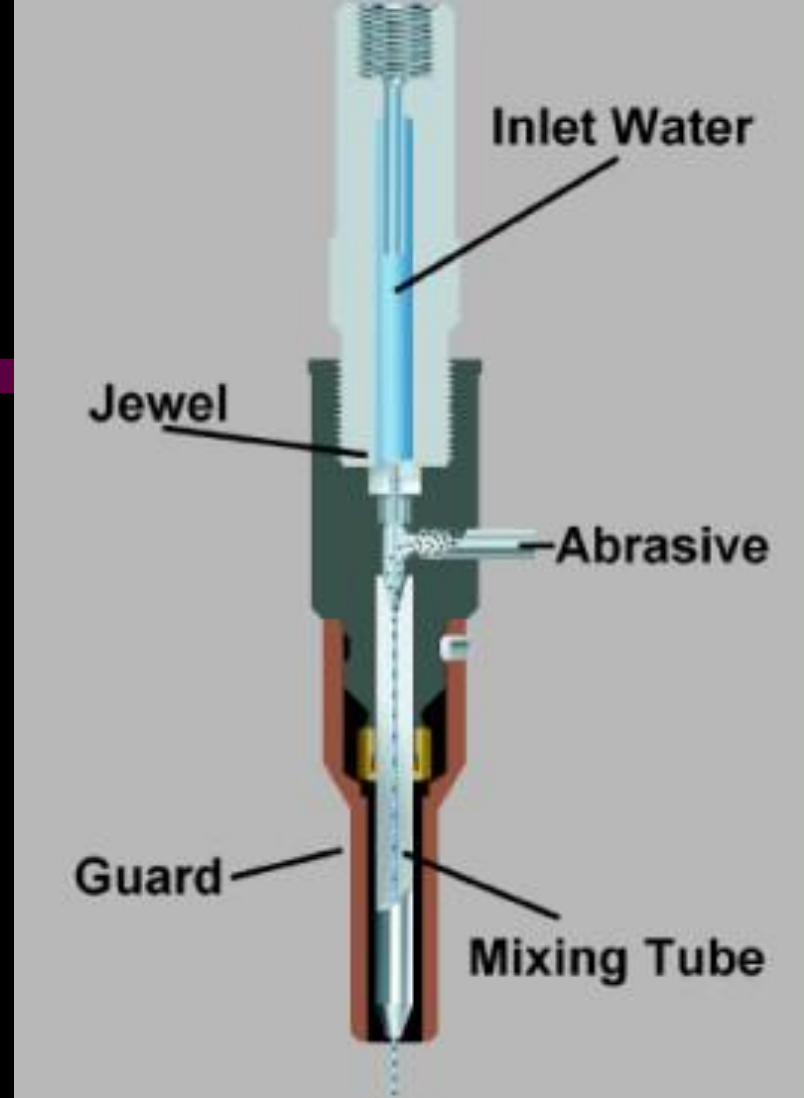
*Abrasive  
Waterjet and  
Waterjet  
examples*





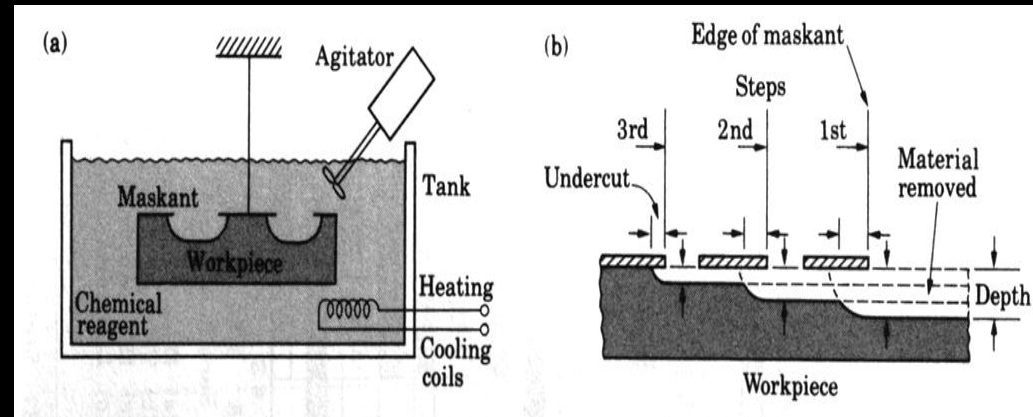
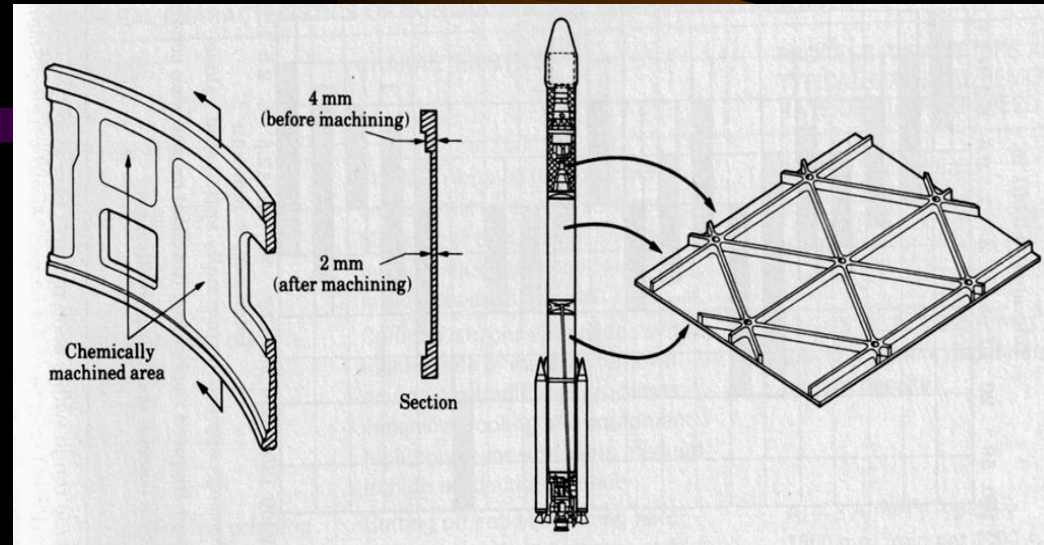
# Abrasive Water Jet

- High pressure water (20,000-60,000 psi)
- Educt abrasive into stream
- Can cut extremely thick parts (5-10 inches possible)
  - Thickness achievable is a function of speed
  - Twice as thick will take more than twice as long
- Tight tolerances achievable
  - Current machines 0.002" (older machines much less capable ~ 0.010")
- Jet will lag machine position, so controls must plan for it



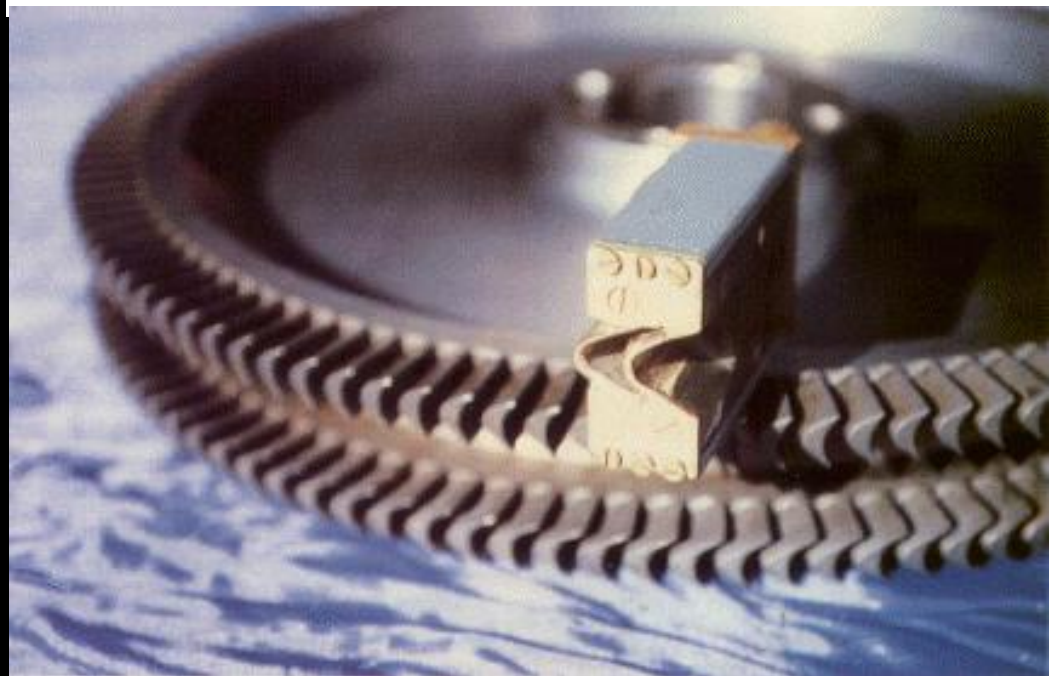
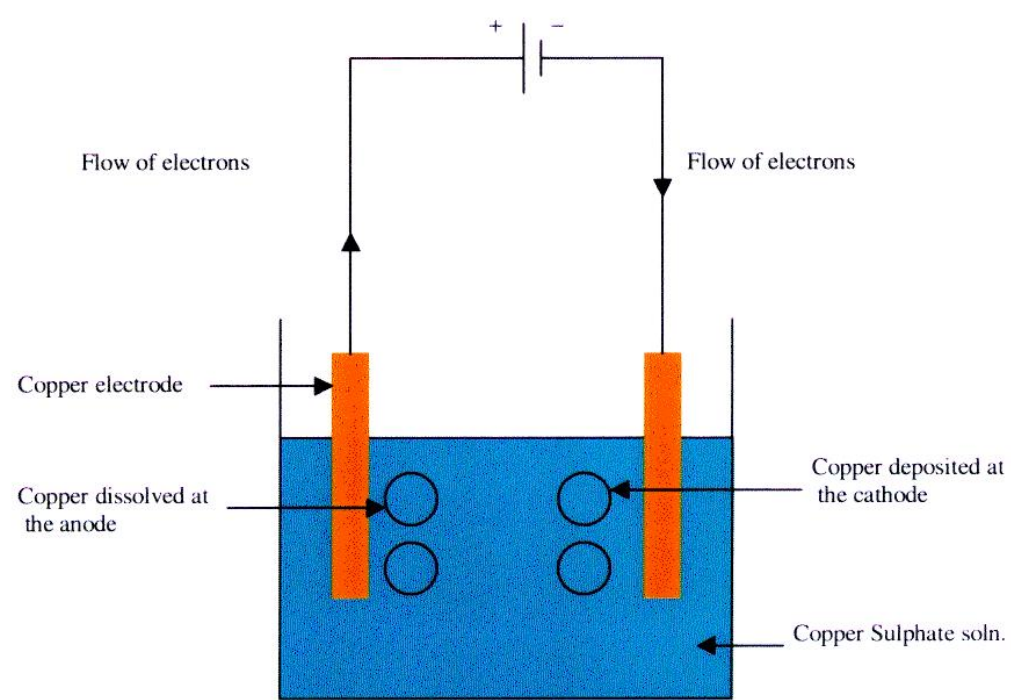
# Chemical Machining (Chemilling)

- Applications:
  - Aerospace industry
  - Engraving
  - Circuit boards
- A maskant is applied over areas you don't want to machine
  - Photochemical methods
  - Apply maskant to entire surface and use laser to cut
- Place the entire part in a chemical bath (acid or alkali depending upon the metal)
- Control temperature and time of exposure to control material removal



# *Electro-Chemical Machining (ECM)*

- Works on the principle of electrolysis – accelerated chemilling
- Die is progressively lowered into workpiece as workpiece is dissociated into ions by electrolysis
- Electrolytic fluid flows around workpiece to remove ions and maintain electrical current path
- Low DC voltage, very High current (700 amps)



# *Electrochemical grinding*

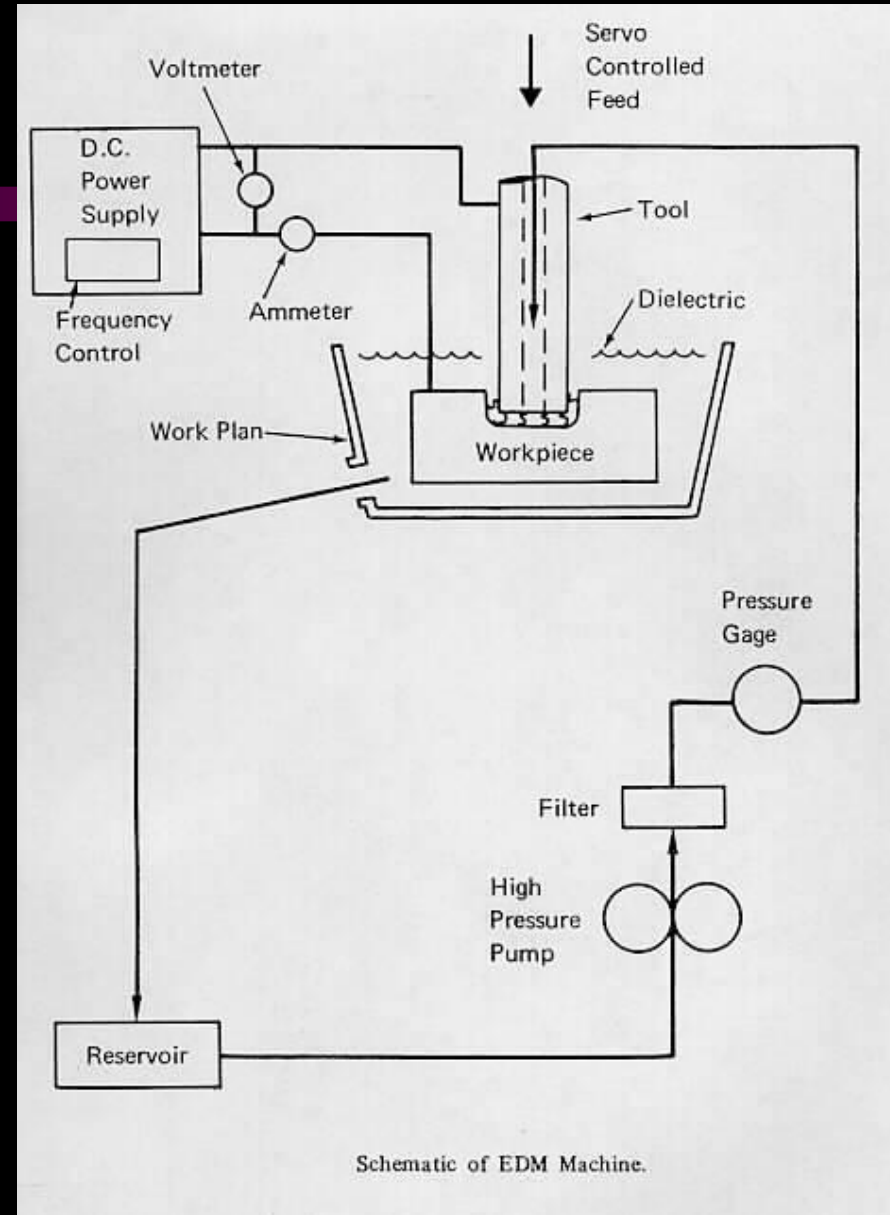
- Combines electrochemical machining with conventional grinding
  - Grinding wheel is the cathode
  - Metal bonded wheel with diamond or  $\text{Al}_2\text{O}_3$  abrasive
  - Majority of material removal from electrolytic action (95%) therefore very low wheel wear
  - Much faster than conventional grinding



# Electrode Discharge

## Machining (EDM)

- Direct Competitor of ECM – much more common than ECM
- The tool acts as a cathode (typically graphite) is immersed in a Dielectric fluid with conductive workpiece
- DC voltage ( $\sim 300\text{V}$ ) is applied. As voltage builds up over gap between workpiece and tool, eventually you get dielectric breakdown (sparking at around  $12,000\text{ deg F}$ )
- The sparking erodes the workpiece in the shape of the tool
- The tool is progressively lowered by CNC as the workpiece erodes
- Cycle is repeated at  $200,000\text{-}500,000\text{ Hz}$
- Dielectric:
  - Cools tool and workpiece
  - Flushes out debris from work area



# Die Sinker vs. Wire EDM



- Die sinker EDM
  - The die sinks into the part as it sparks away the workpiece
  - Most common Injection molding die process
- Wire EDM
  - The electrode is a wire that traverses through the part
  - Common for Extrusion Dies



# *Laser Beam Machining*

- Lasers are high intensity focused light sources
  - CO<sub>2</sub>
    - Most widely used
    - Generally more powerful than YAG lasers
    - Cutting operations commonly
  - Nd:YAG (Neodymium ions in an Yttrium Aluminum Garnet)
    - Less powerful
    - Etching/marking type operations more commonly
- Limited in depth of cut (focus of light)
- Would limit workpiece to less than 1 inch (< 1/2" typically)

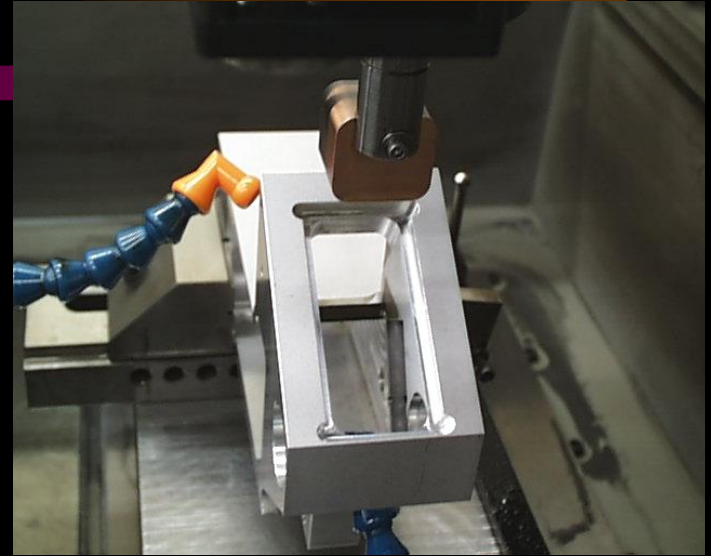
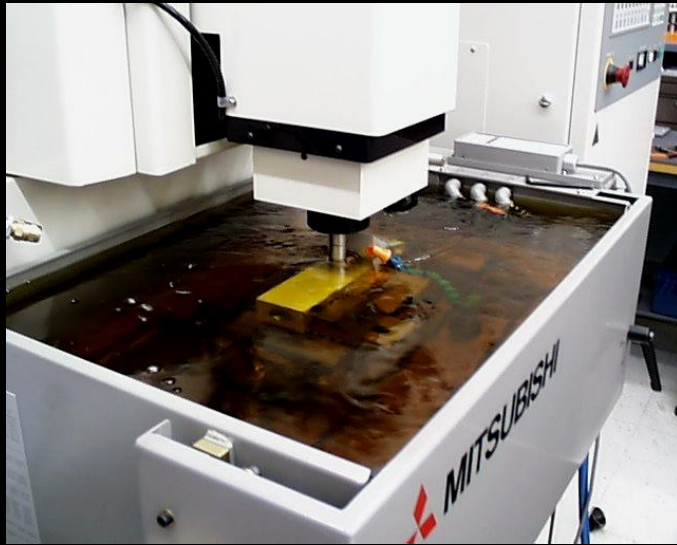
# *Case Study*

- CNC Mill
- CNC Wire EDM
- CNC EDM

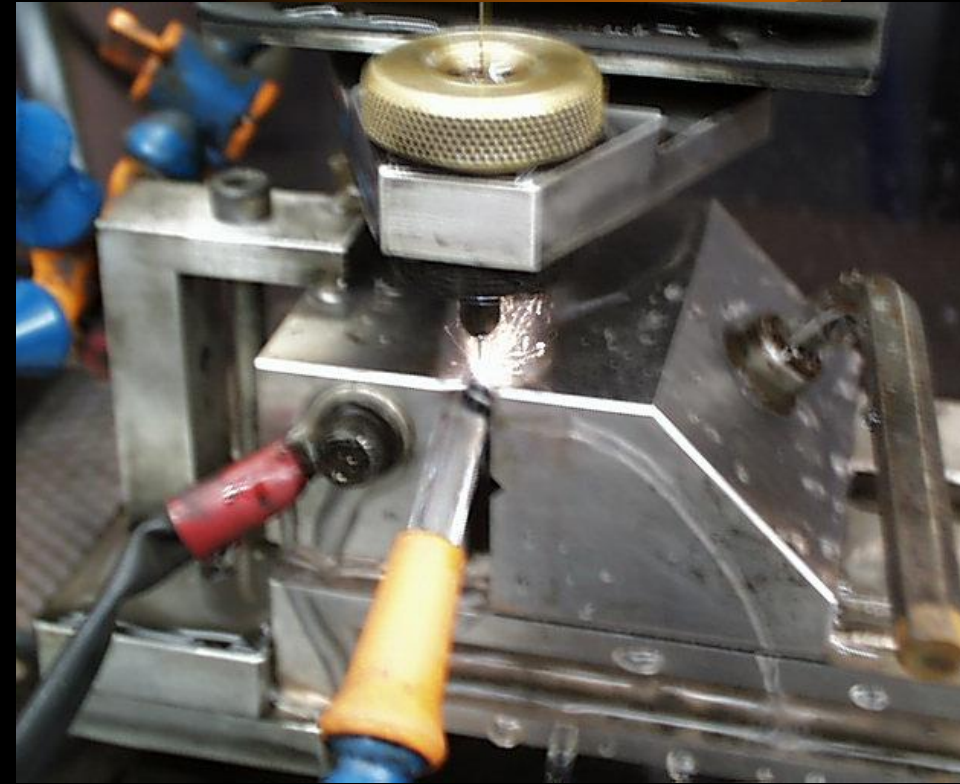
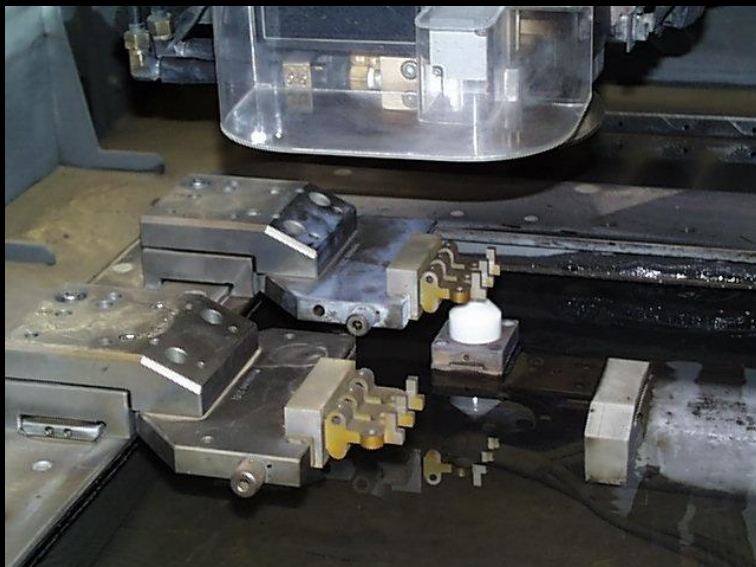




# *Wire EDM (not shown), Die Sinker EDM, Anodized*

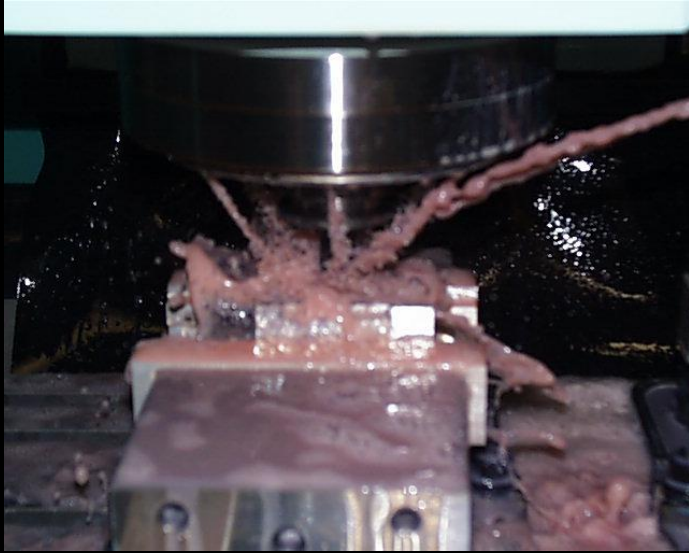


# *Different Part - Wire EDM – profiling and drilling*

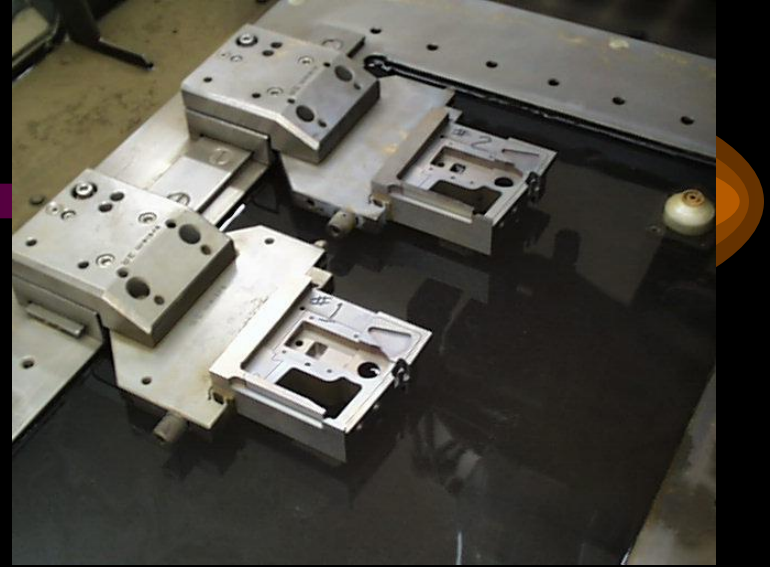




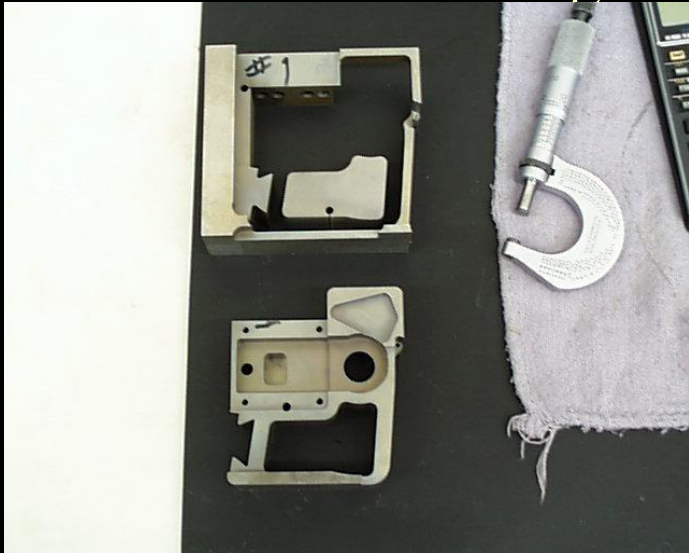
# Case Study Three



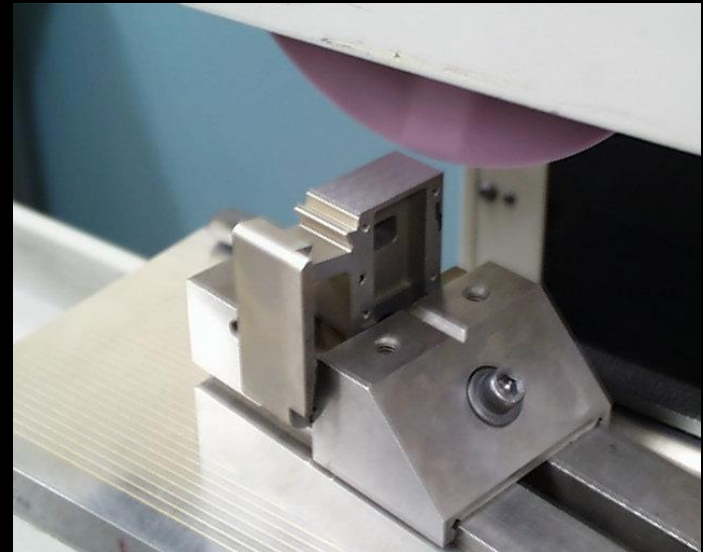
1. CNC Milling



2. Setup on wire EDM



3. QA After wire EDM

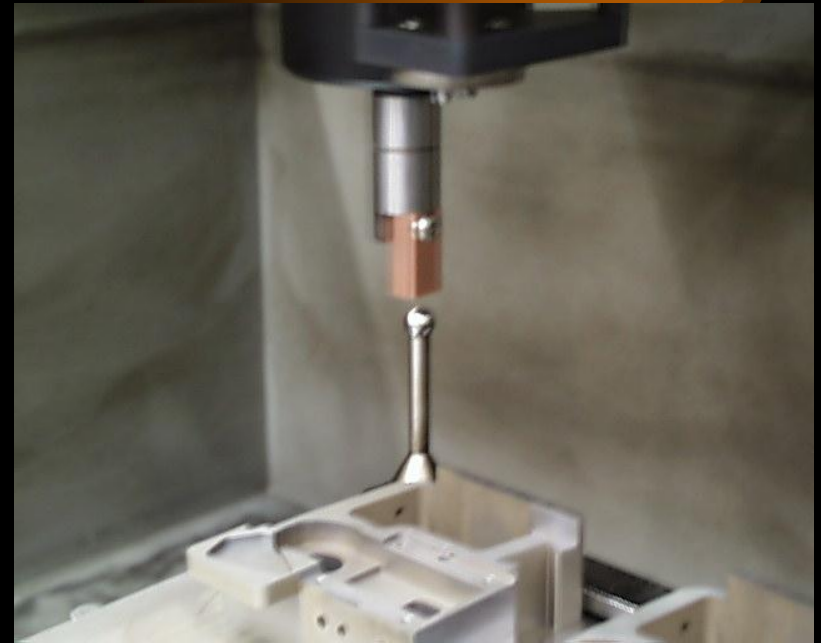


4. Grinding a face on the part

# *Setup of Die Sinker EDM*



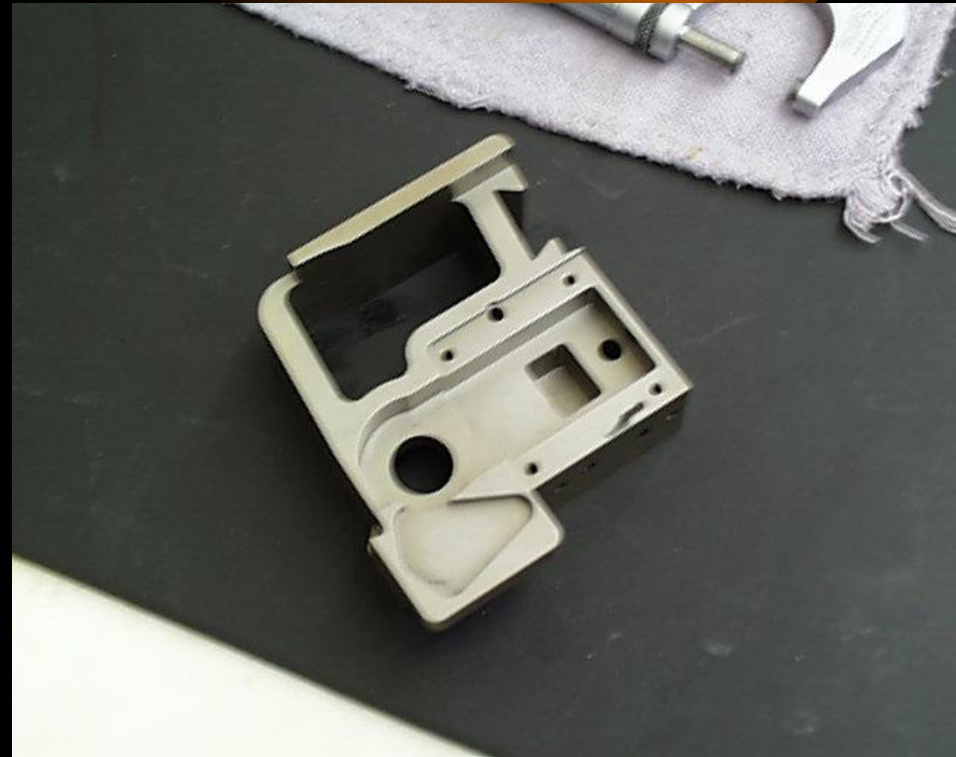
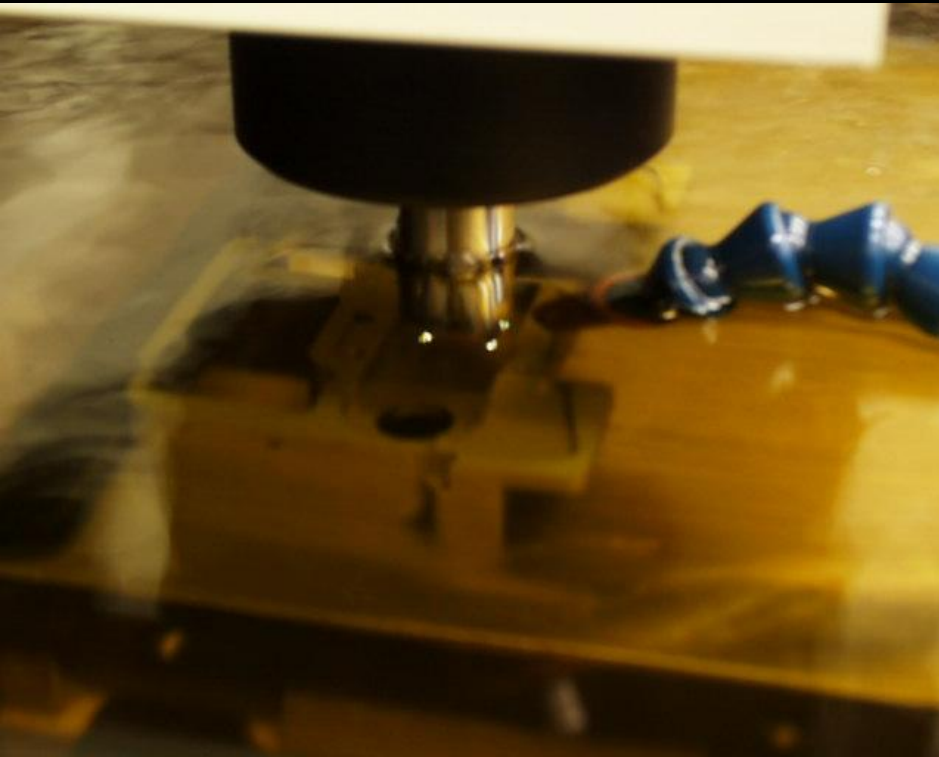
1. Locating parts relative to machine



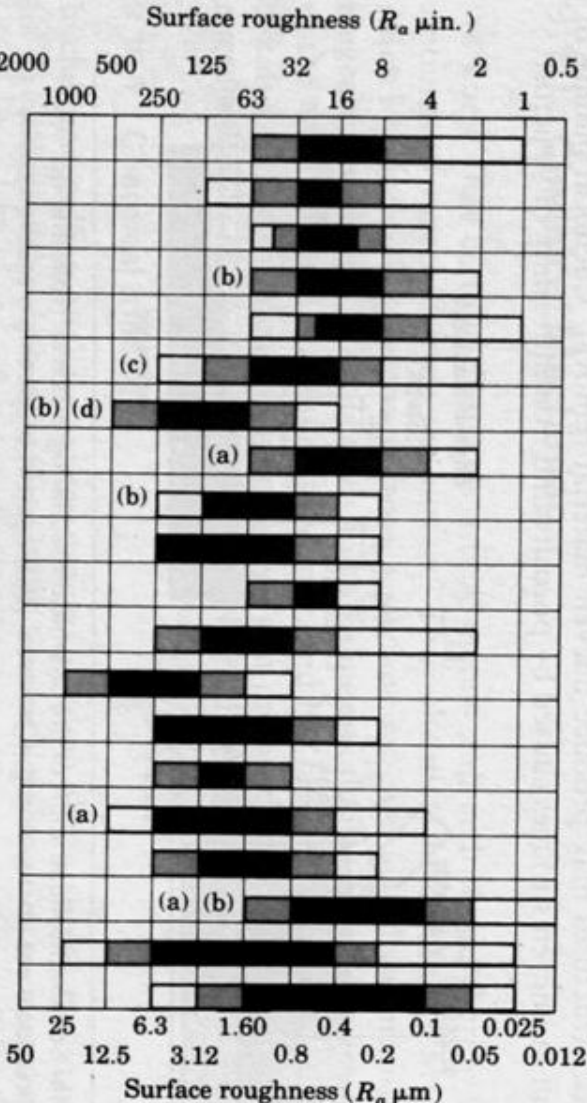
2. Locating the electrode relative to parts setup



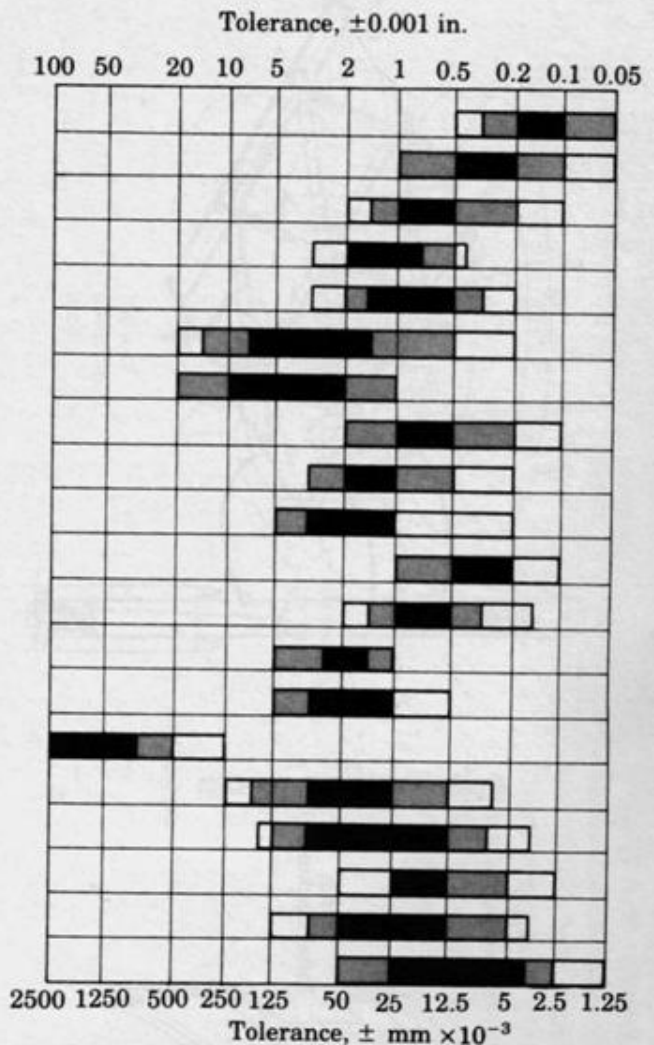
# *Die Sinker in action and finished product*



# Overall Machining Tolerances and Surface Roughness



- MECHANICAL**
  - Abrasive-flow machining
  - Low-stress grinding
  - Ultrasonic machining
- ELECTRICAL**
  - Electrochemical deburring
  - Electrochemical grinding
  - Electrochemical milling (frontal)
  - Electrochemical milling (side wall)
  - Electrochemical polishing
  - Shaped-tube electrolytic machining
- THERMAL**
  - Electron-beam machining
  - Electrical-discharge grinding
  - Electrical-discharge machining (finishing)
  - Electrical-discharge machining (roughing)
  - Laser-beam machining
  - Plasma-beam machining
- CHEMICAL**
  - Chemical machining
  - Photochemical machining
  - Electropolishing
- CONVENTIONAL MACHINING**
  - Turning
  - Surface grinding



Notes: (a) Depends on state of starting surface.  
 (b) Titanium alloys are generally rougher than nickel alloys.  
 (c) High-current-density areas.  
 (d) Low-current-density areas.

Average application (normally anticipated values)  
 Less frequent application (unusual or precision conditions)  
 Rare (special operating conditions)